

RoHS Compliant

REV	MODIFICATION	DATE	DRAW
A0	Release To Production	13-03-12	Ivy
A1	Release To ECN20150101	08-01-15	Michelle

Specification

- 1.Current Rating:1A
- 2.Voltage Rating:125V AC
- 3.Contact Resistance:20mΩ Max.(Initial) 40mΩ Max.(Final)
- 4.Insulation Resistance:100MΩ Min. At 500V
- 5.Dielectric Withstanding Voltage:AC250V/Minute
- 6.Operating Temperature:-40°C~+85°C

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.25mm
- 3.Contact Pin:Copper Alloy T=0.30mm

Finish:

- 1.Housing:HTN UL94V-0 Nature H.F
- 2.Tab:Matte Tin Plated Over Nickel
- 3.Contact Pin:Matte Tin Plated Over Nickel
- 4.Plating:Matte Tin Plated Over Nickel

Part No.: 4 3 1 8 - S x x R x H

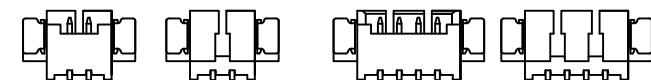
No. Of Pin
02~15

Packing
T:Tube
R:T&R

Housing Material
H:HTN UL94V-0
Nature H.F

02~03P

04~15P



PIN	DIM.A	DIM.B	DIM.C	DIM.D
02	1.25	3.05	4.25	7.65
03	2.50	4.30	5.50	8.90
04	3.75	5.55	6.75	10.15
05	5.00	6.80	8.00	11.40
06	6.25	8.05	9.25	12.65
07	7.50	9.30	10.50	13.90
08	8.75	10.55	11.75	15.15
09	10.00	11.80	13.00	16.40
10	11.25	13.05	14.25	17.65
11	12.50	14.30	15.50	18.90
12	13.75	15.55	16.75	20.15
13	15.00	16.80	18.00	21.40
14	16.25	18.05	19.25	22.65
15	17.50	19.30	20.50	23.90

RECOMMENDED P.C.B LAYOUT

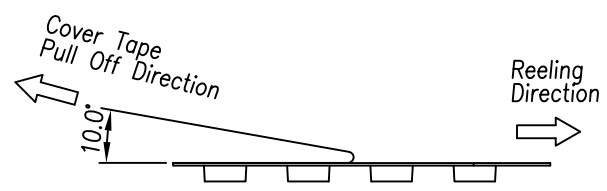
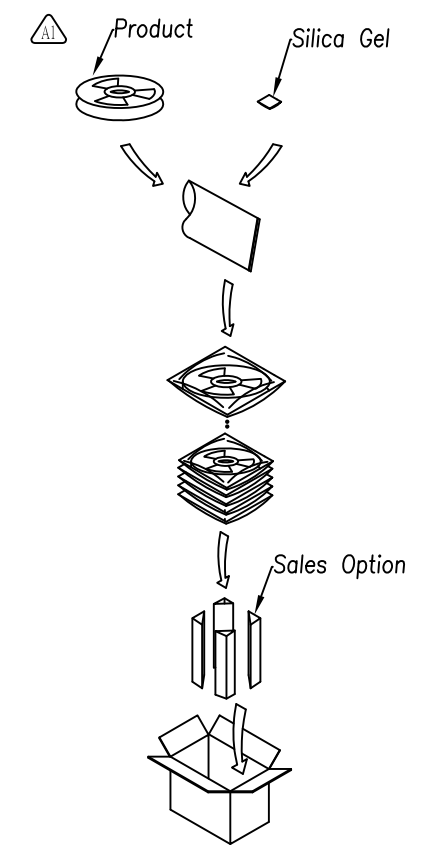
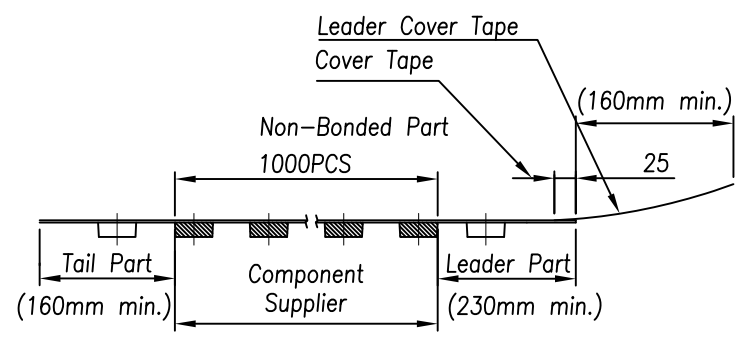
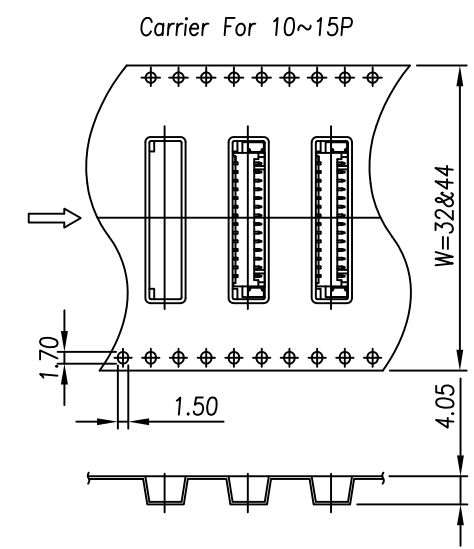
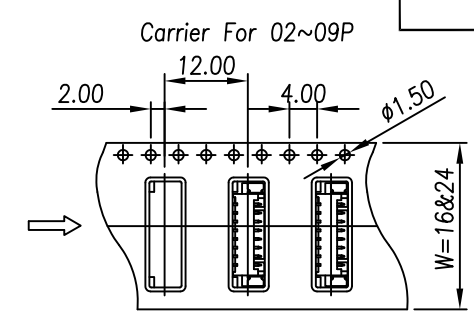
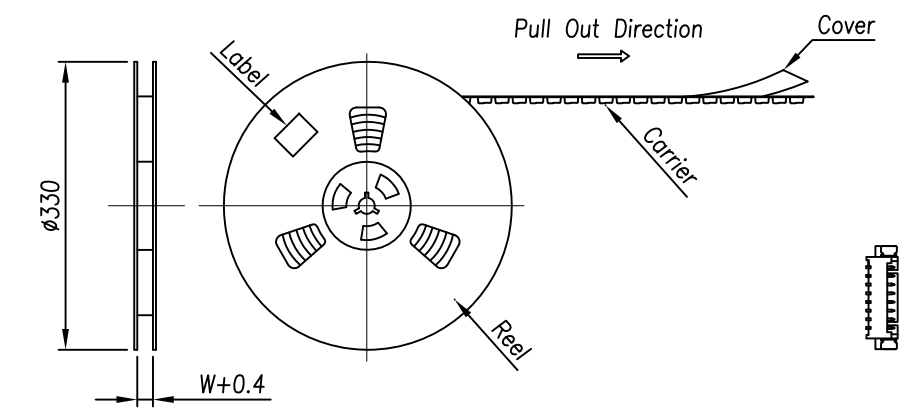


易昕企業有限公司
LEAMAX ENTERPRISE CO., LED.

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ.	TITLE: Wire To Board Wafer 1.25mm 90° SMT Single Row			
.X± 0.35	X*± 2°	APR. Chen 14-09-18	DWG NO.4318-S03			
.XX± 0.25	.X*± 1°	CHK. Huang 03-09-18	UNITS: MM	PN:4318-SxxRxH		
.XXX± 0.15	.XX*± 0.5°	DRA. Michelle 08-01-15	SIZE: A4	SCALE: FREE	SHEET: 1/2	REV. A1 V

A
B
C
D
E
F

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Notes:
1. Material : PS
2. Part No.: 4318-SxxRRH

PIN NO.	W ±0.30	PCS / REEL
02 ~ 03	16	1000
04 ~ 09	24	
10 ~ 13	32	
14 ~ 15	44	

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.xxx± 0.15	.xx.*± 0.5°	DRA. Michelle 08-01-15	SIZE: A4	SCALE: FREE
			SHEET: 2/2	REV. A1
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A
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